

# QSC112, QSC113, QSC114 Plastic Silicon Infrared Phototransistor

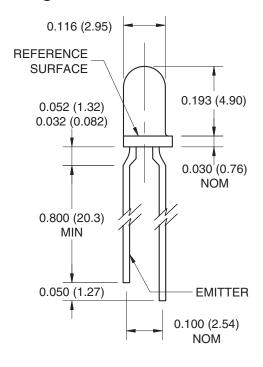
#### **Features**

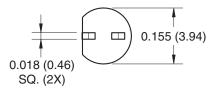
- Tight production distribution
- Steel lead frames for improved reliability in solder mounting
- Good optical-to-mechanical alignment
- Plastic package is infrared transparent black to attenuate visible light
- Can be used with QECXXX LED
- Black plastic body allows easy recognition from LED

## **Description**

The QSC112/113/114 is a silicon phototransistor encapsulated in an infrared transparent, black T-1 package.

## **Package Dimensions**



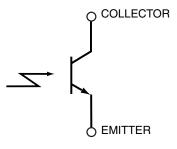


#### Notes:

- 1. Dimensions of all drawings are in inches (mm).
- 2. Tolerance is ±0.10 (.25) on all non-nominal dimensions unless otherwise specified.



### **Schematic**



# **Absolute Maximum Ratings** (T<sub>A</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Rating	Units
T <sub>OPR</sub>	Operating Temperature	-40 to +100	°C
T <sub>STG</sub>	Storage Temperature	-40 to +100	°C
T <sub>SOL-I</sub>	Soldering Temperature (Iron) <sup>(2,3,4)</sup>	240 for 5 sec	°C
T <sub>SOL-F</sub>	Soldering Temperature (Flow) <sup>(2,3)</sup>	260 for 10 sec	°C
V <sub>CE</sub>	Collector-Emitter Voltage	30	V
V <sub>EC</sub>	Emitter-Collector Voltage	5	V
P <sub>D</sub>	Power Dissipation <sup>(1)</sup>	100	mW

#### Notes:

- 1. Derate power dissipation linearly 1.33 mW/°C above 25°C.
- 2. RMA flux is recommended.
- 3. Methanol or isopropyl alcohols are recommended as cleaning agents.
- 4. Soldering iron 1/16" (1.6mm) minimum from housing.

# **Electrical/Optical Characteristics** (T<sub>A</sub> =25°C)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
λ <sub>PS</sub>	Peak Sensitivity Wavelength			880		nm
Θ	Reception Angle			±8		0
I <sub>CEO</sub>	Collector-Emitter Dark Current	V <sub>CE</sub> = 10 V, Ee = 0			100	nA
BV <sub>CEO</sub>	Collector-Emitter Breakdown	I <sub>C</sub> = 1 mA	30			V
BV <sub>ECO</sub>	Emitter-Collector Breakdown	I <sub>E</sub> = 100 μA	5			V
I <sub>C(ON)</sub>	On-State Collector Current QSC112	Ee = 0.5 mW/cm <sup>2</sup> , $V_{CE} = 5 V^{(5)}$	1		4	mA
	On-State Collector Current QSC113		2.40		9.60	
	On-State Collector Current QSC114		4.00			
V <sub>CE(sat)</sub>	Saturation Voltage	Ee = $0.5 \text{ mW/cm}^2$ , $I_C = 0.5 \text{ mA}^{(5)}$			0.4	V
t <sub>r</sub>	Rise Time	$V_{CC} = 5 \text{ V}, R_L = 100 \Omega, I_C = 2 \text{ mA}$		5.0		μs
t <sub>f</sub>	Fall Time			5.0		

#### Note:

5.  $\lambda$  = 880 nm, AlGaAs.

# **Typical Performance Curves**

Figure 1. Light Current vs. Radiant Intensity

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V<sub>CE</sub> = 5V

GaAs Light Source

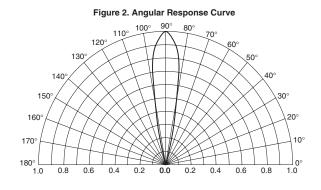
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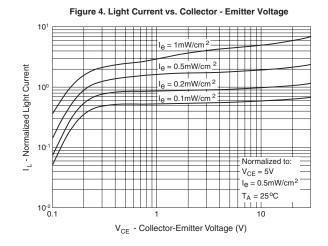
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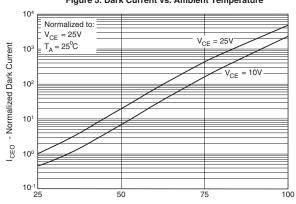
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E<sub>e</sub> - Radiant Intensity (mW/cm<sup>2</sup>)



 $V_{CE}$  - Collector-Emitter Voltage (V)





 $\rm T_A$  - Ambient Temperature (  $^{\rm o}\rm C)$ 

UniFET™ UltraFET® VCX™ Wire™

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Rev. I20